

# Supplementary Information

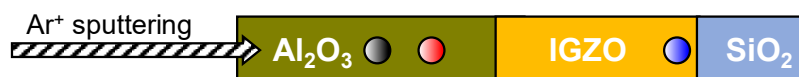
## Suppression of redox reaction between IGZO surface and reducing agent TMA using oxidizing agent fluorine treatment

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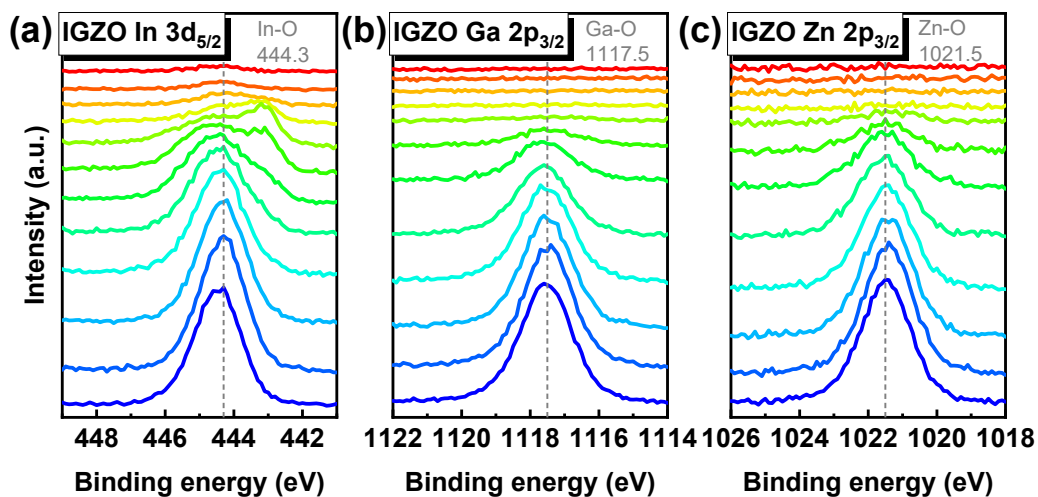
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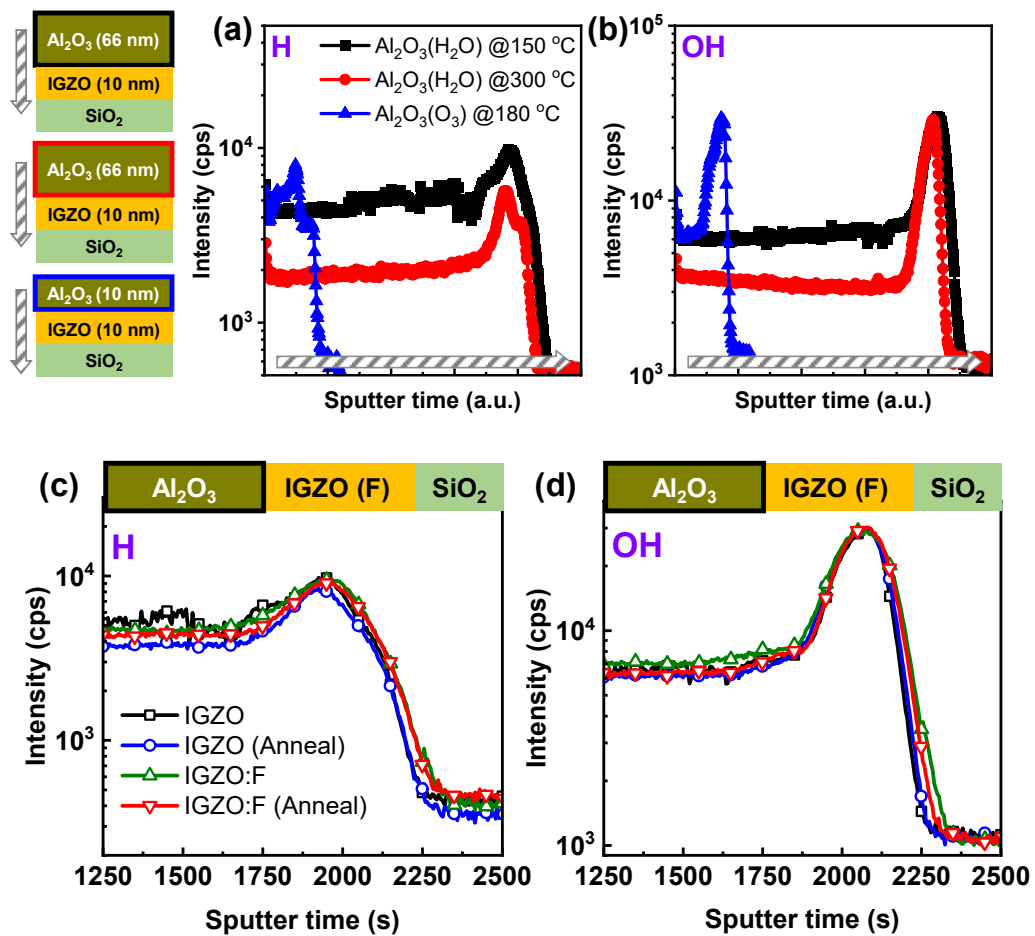


After charge referencing by adventitious carbon (AdC) 1s at 284.8 eV

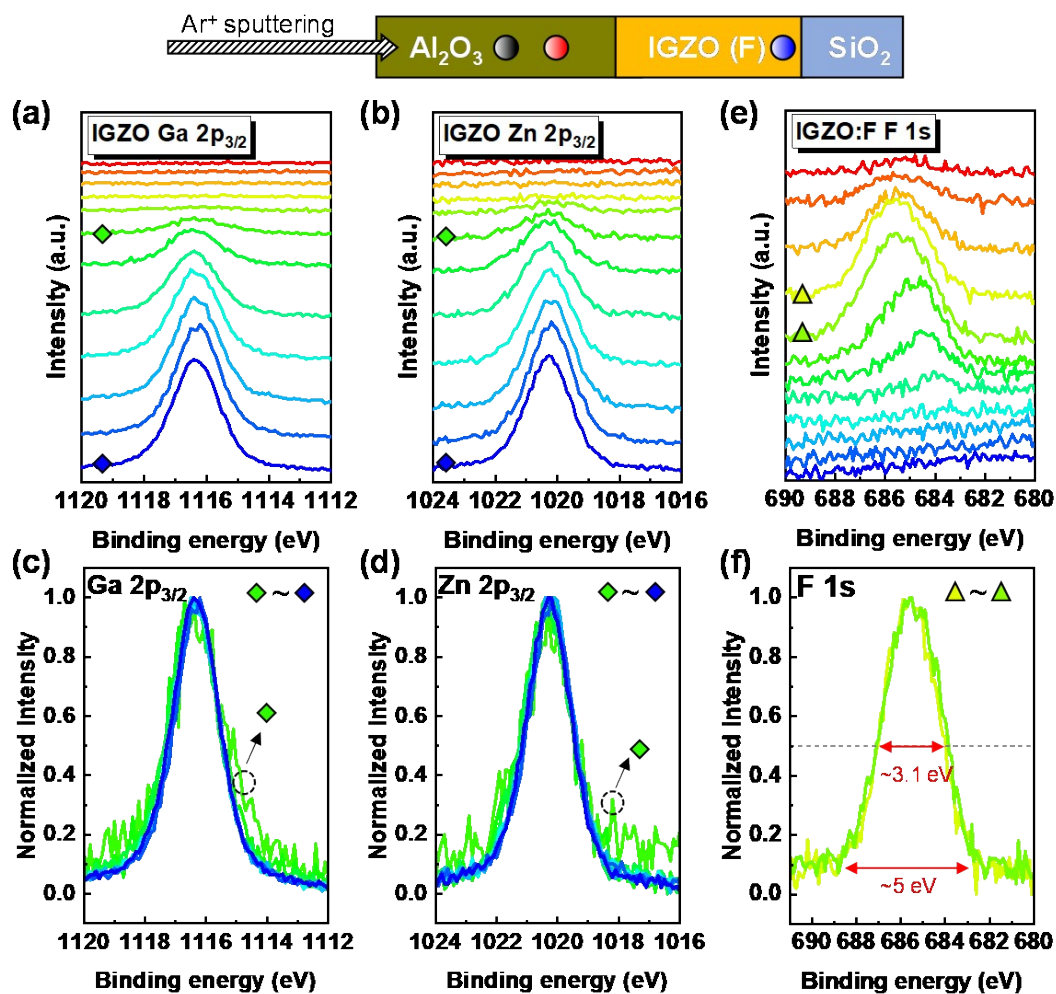


**Fig. S 1.** The depth-resolved XPS (a) In  $3d_{5/2}$ , (b) Ga  $2p_{3/2}$ , and (c) Zn  $2p_{3/2}$  core level spectra of standard  $\text{Al}_2\text{O}_3/\text{IGZO}$  stack after charge referencing by adventitious carbon (AdC) 1s at 284.8 eV. The gray dashed lines indicate the peak binding energy (BE) values for each metal oxide, that are in good agreement with the NIST database.<sup>1</sup>

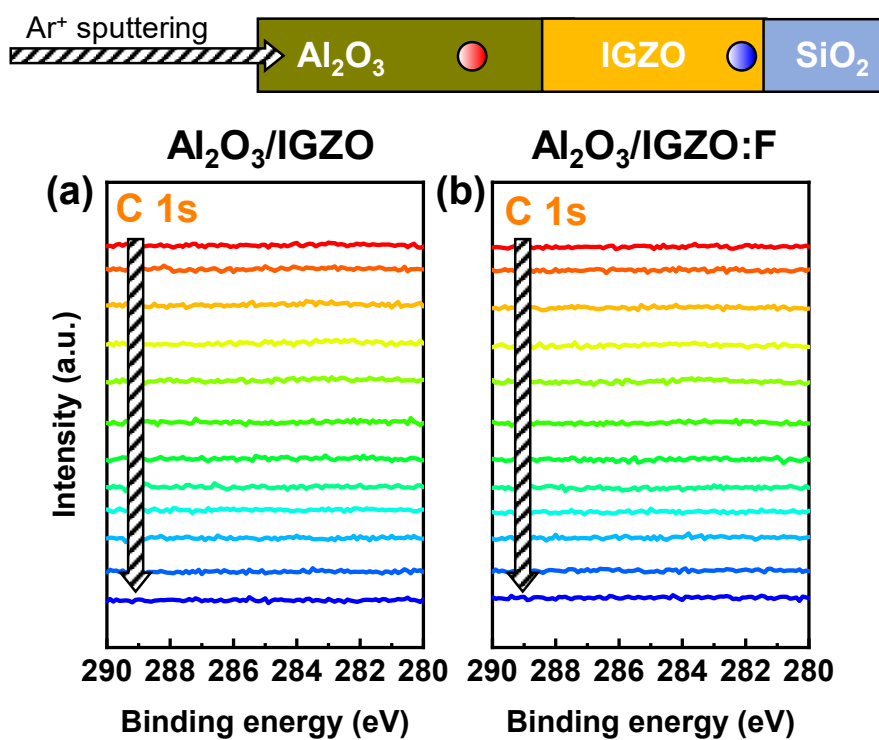
[1] NIST X-ray Photoelectron Spectroscopy Database, NIST Standard Reference Database Number 20, <https://srdata.nist.gov/xps/>, DOI: 10.18434/T4T88K.



**Fig. S 2** TOF-SIMS (a) H and (b) OH profiles of as-prepared Al<sub>2</sub>O<sub>3</sub>/IGZO stacks with respect to ALD-Al<sub>2</sub>O<sub>3</sub> parameters. The gray patterned arrow represents the incident primary beam. The short sputter time of Al<sub>2</sub>O<sub>3</sub> at a substrate temperature of 180 °C using O<sub>3</sub> gas as an oxidant (blue) is due to the thickness of 10 nm-thick Al<sub>2</sub>O<sub>3</sub>. Enlarged TOF-SIMS (c) H and (d) OH profiles near the Al<sub>2</sub>O<sub>3</sub>/IGZO (F) interfaces, where the Al<sub>2</sub>O<sub>3</sub> was deposited at a substrate temperature of 150 °C using H<sub>2</sub>O as an oxidant because of the highest H related concentrations. The annealing was conducted by a hot plate at 180 °C for 1 hr, which was the same process condition used for TFT fabrication.



**Fig. S 3** The depth-resolved XPS (a) Ga 2p<sub>3/2</sub> and (b) Zn 2p<sub>3/2</sub> core level raw spectra of standard Al<sub>2</sub>O<sub>3</sub>/IGZO stack. The normalized (c) Ga 2p<sub>3/2</sub> and (d) Zn 2p<sub>3/2</sub> core level raw spectra of standard Al<sub>2</sub>O<sub>3</sub>/IGZO stack. (e) The depth-resolved XPS F 1s core level raw spectra of Al<sub>2</sub>O<sub>3</sub>/IGZO:F stack. (f) The normalized F 1s core level raw spectra of Al<sub>2</sub>O<sub>3</sub>/IGZO:F stack.



**Fig. S 4** The depth-resolved XPS C 1s core level raw spectra of (a)  $\text{Al}_2\text{O}_3/\text{IGZO}$  and (b)  $\text{Al}_2\text{O}_3/\text{IGZO:F}$  stacks.